

ABSTRACT OF THE DISCLOSURE

A multi-chip package (MCP) that incorporates a leadframe pad arranged and configured to allow the active surface of a first chip to be mounted on a lower surface of the leadframe pad and a second chip to be mounted on an upper surface of the leadframe pad whereby the first and second chips may be mounted and wire bonded to inner leads without inverting the leadframe, thereby reducing the likelihood of damage during manufacturing and allowing for a reduction in package thickness. The first and second chips, as well as the bonding wires that connect the chips to inner leads of the leadframe may be sealed in a package body. Outer leads extending from the package body and integrally formed with the inner leads may be formed to provide finished packages having a variety of mounting configurations for attachment to circuit boards or other applications.